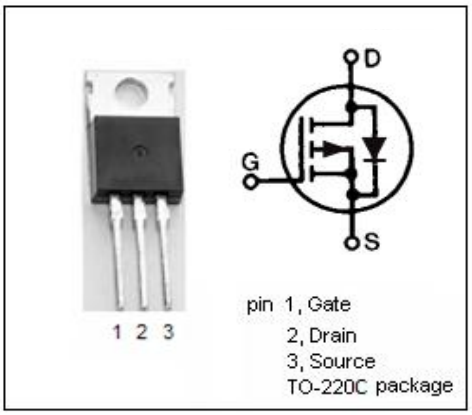
isc P-Channel MOSFET Transistor IXTP52P10P



• FEATURES

- Static drain-source on-resistance:
  $R_{DS}(on) \leqslant 50m\Omega$
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• APPLICATION

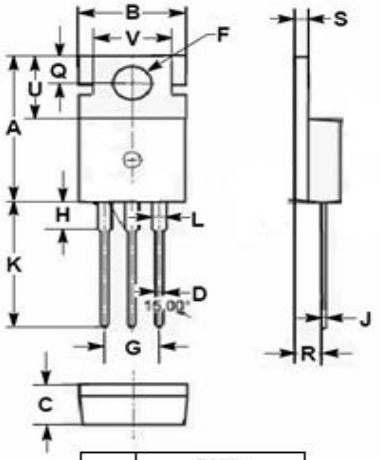
- Hight side switching
- Current regulators
- Automatic test equipment

• ABSOLUTE MAXIMUM RATINGS(T_a=25℃)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current-Continuous	-52	A
I_{DM}	Drain Current-Single Pulsed	-130	A
P_D	Total Dissipation @T_C=25℃	300	W
T_j	Operating Junction Temperature	-55~150	℃
T_{stg}	Storage Temperature	-55~150	℃

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(j-c)}$	Channel-to-case thermal resistance	0.42	℃/W



DIM	mm MIN	MAX
A	15.50	15.90
B	9.90	10.20
C	4.20	4.50
D	0.70	0.90
F	3.40	3.70
G	4.98	5.18
H	2.68	2.90
J	0.44	0.60
K	13.00	13.40
L	1.10	1.45
Q	2.70	2.90
R	2.30	2.70
S	1.29	1.35
U	6.45	6.65
V	8.66	8.86

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ELECTRICAL CHARACTERISTICS

T_C=25℃ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V; I_D= -250 μA	-100			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}; I_D= -250 μA	-2.5		-4.5	V
$R_{DS(on)}$	Drain-Source On-Resistance	V_{GS}= -10V; I_D= -26A			50	mΩ
I_{GSS}	Gate-Source Leakage Current	V_{GS}= ±20V			±100	nA
I_{DSS}	Drain-Source Leakage Current	V_{DS}= V_{DSS}; V_{GS}= 0V			-10	μA
		V_{DS}= V_{DSS}; V_{GS}= 0V; T_J=125℃			-150	
V_{SD}	Diode forward voltage	I_F= -26A; V_{GS} = 0V			-3.5	V